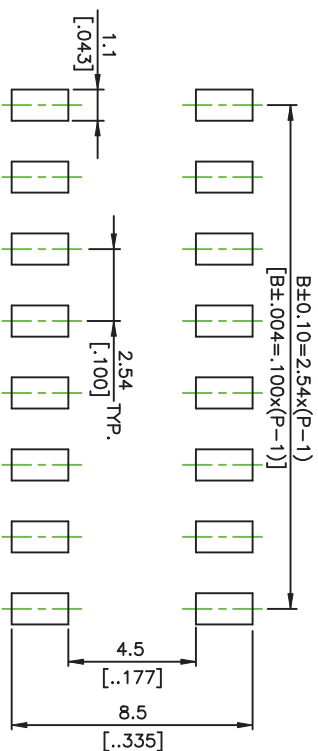
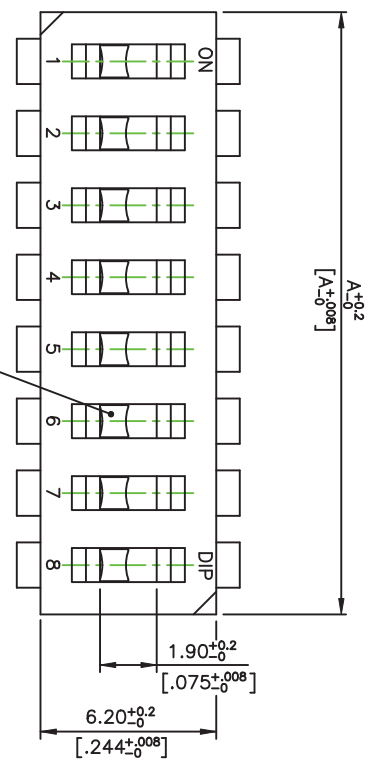
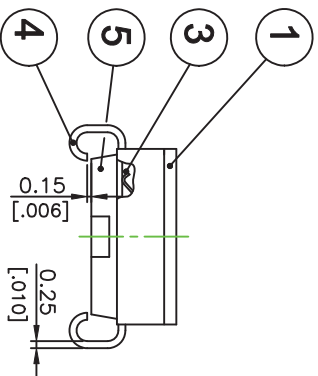
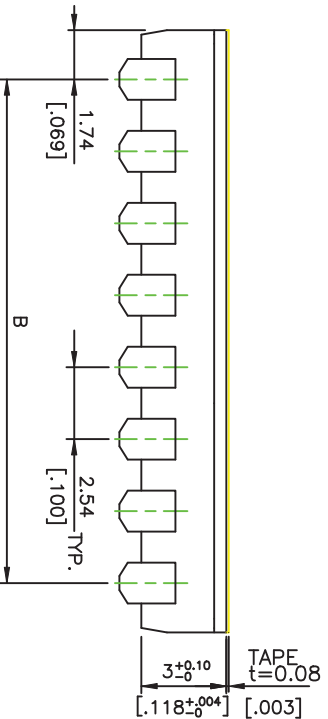


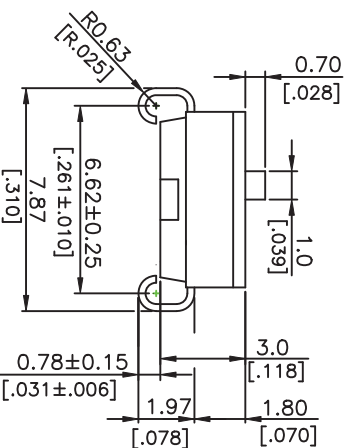
- NOTE:**
1. ALL DIMENSIONS ARE IN MILLIMETERS, BRACKETED DIMENSIONS ARE IN INCHES
 2. GENERAL TOLERANCES: MAX ±0.20mm.
 3. DJ(R)-02 / DJ(R)-03 ARE WITHOUT "DIP" PRINTING.



P.C.B. LAYOUT



DJR-V SERIES



DJ-V SERIES

符號	原尺寸	修改後尺寸	變更日期
1	(A)		
2	(B)		
3	(C)		
4	(D)		
5	(E)		

SCALE (比例) : 5 : 1

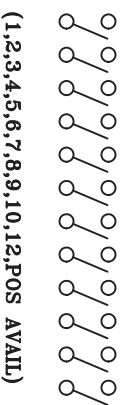
FILE NAME : Y1307

TITLE 圖名	J TYPE DIP SWITCH		
DWG NO. 圖號	DJR-08-T-V		
REV. 版本	DATE 日期	MAY - 16 - 2013	SHEET 張數
CHECKED BY 審核	RICHARD	DRAWN BY 製圖	IRENE

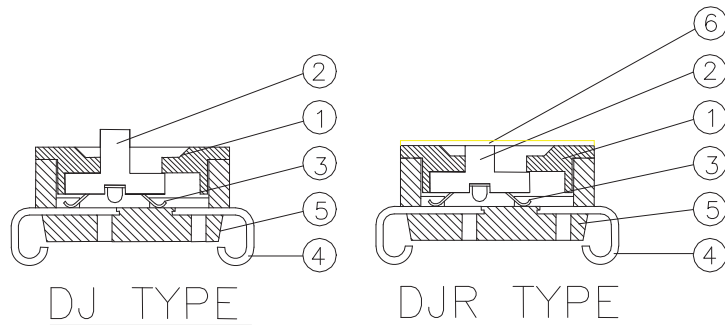
德利威電子股份有限公司
DAILYWELL ELECTRONICS CO.,LTD.

PROD. NO.	NO. OF POS.	DIM. A	DIM. B
DJ -12-V	12	31.42[1.237]	27.94[1.100]
DJ -10-V	10	26.34[1.037]	22.86[.900]
DJ -09-V	9	23.80[.937]	20.32[.800]
DJ -08-V	8	21.26[.837]	17.78[.700]
DJ -07-V	7	18.72[.737]	15.24[.600]
DJ -06-V	6	16.18[.637]	12.70[.500]
DJ -05-V	5	13.64[.537]	10.16[.400]
DJ -04-V	4	11.10[.437]	7.62[.300]
DJ -03-V	3	8.56[.337]	5.08[.200]
DJ -02-V	2	6.02[.237]	2.54[.100]

SCHEMATIC(TYP.)



ITEM	DESC.	Q'TY	MATERIALS	TREATMENT	REMARK
1.	COVER	1	HIGH - TEMP. THERMOPLASTIC PPS UL 94V-0	MOLDED BLACK	-
2.	ACTUATOR	1	THERMOPLASTIC NYLON UL 94V-0	MOLDED WHITE	-
3.	CONTACT	1	ALLOY-COPPER	GOLD PLATED AT CONTACT AREA.	-
4.	TERMINAL	1	BRASS	□= GOLD PLATED	-
				P= GOLD PLATED AT CONTACT AREA, TIN/LEAD AT TERMINATION AREA.	-
5.	BASE	1	THERMOPLASTIC PPS UL 94V-0	MOLDED BLACK	-
6.	TAPE	1	KAPTON	-	-



Remark:

① Prod. No. : D J □ - □ □ □ □ □

Actuator Type:

□ = Raised Actuator.

R = Recessed Actuator.

Package Style:

□ = Tube

T/R = Tape & Reel

Number Of Position:

02 = 2 Position

03 = 3 Position

04 = 4 Position

05 = 5 Position

06 = 6 Position

07 = 7 Position

08 = 8 Position

09 = 9 Position

10 = 10 Position

12 = 12 Position

Seal:

□ = Regular

T = Top Tape Sealed

□ = Gold Plated

P = Tin/Lead Plated

② The amounts of actuators, contacts, and terminals are based on position number.

	工(工變)00029	楊豐富
B	DWG. REL	楊豐富
A	ECO. NO	APPD
REV		

TITLE:	S.M.T TYPE DIP SWITCHES	APPD. : 楊豐富
PRROD. NO. : DJ(R)-□□		CHKD. : 吳振中
		PR. : 楊佩儒

1. Style:

This specification describes "DUAL IN-LINE PACKAGE SWITCHES" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating Temperature Range : -20°C ~ +85°C

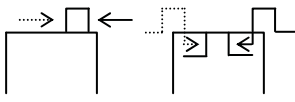
1.2 Storage Temperature Range : -40°C ~ +85°C

2. Current Range :

2.1 Non-Switching : 100mA, 50V DC

2.2 Switching : 25mA , 24V DC

3. Type of Actuation: Actuated by sliding**4. Test Sequence :**

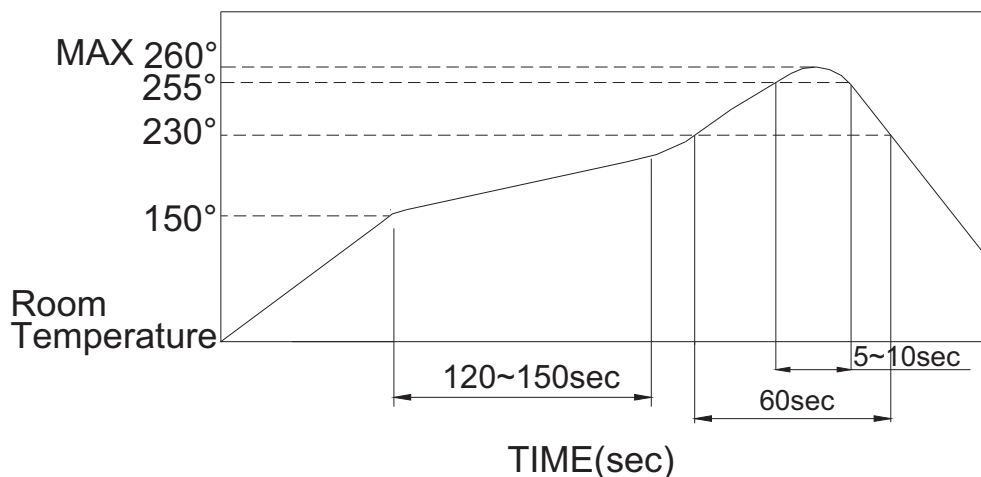
	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
ELECTRIC PERFORMANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
	2	Contact Resistance	①To be measured between the two terminals associated with each switch pole. ②Measurements shall be made with a 1kHz shall current contact resistance meter.	50mΩ max. (initial)
	3	Insulation Resistance	500V DC, 1 minute ± 5 sec.	100MΩ min.
	4	Dielectric withstanding Voltage	500V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.
	5	Capacitance	1 MHz ± 10 kHz	5 pF max.
MECHANICAL PERFORMANCE	6	Operation Force	Applied in the direction of operation. ON→OFF OFF→ON 	1000gf max (9.8N max)

MECHANICAL PERFORMANCE	7	Stop Strength	A static load of 1 kgf is applied in the operating direction and pulling direction operated for a period of 15 seconds.	There shall be no sign of damage mechanically.		
	8	Soldering Heat Resistance	1.Soldering Temperature :		As shown in item 2~6	
			PROD SERIES	TEMP		TIME
			THROUGH HOLE TYPE NDI(R)-V	260°C±5°C		5±1 sec.
			SMT TYPE DM(R) 、 DL(R)-V	SEE PAGE 4/4		
	2.Duration of Solder Immersion: 5±1 sec. 3.Frequency of Soldering Process: 2 times max. (PCB is 1.6mm in thickness.)					
9	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F ①Frequency: 10-55-10 Hz 1 min/cycle. ②Direction: 3 vertical directions including the direction of operation. ③Test Time: 2 hours each direction.	As shown in item 2~6			
10	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F ①Acceleration: 50G. ②Action Time : 11 ± 1 m sec. ③Testing Direction: 6 sides. ④Test cycle : 3 times in each direction	As shown in item 2~6			
11	Solderability	①THROUGH HOLE TYPE Soldering Temperature:245±3°C Lead-Free solder : M705E JIS Z 3282 Class A (Tin 96.5% , Silver 3% , Copper 0.5%) ②Flux: 5-10 seconds. ③Duration of solder Immersion: 3±0.5 sec. ④ SMT TYPE SEE PAGE 4/4	No anti-soldering and the coverage of dipping into solder must more than 75% was requested.			

DURABILITY	12	Operation Life	Measurements shall be made following the test set forth below: ①25 mA, 24V DC resistive load ②Rate of Operation: 15~20 cycles/minute ③Cycle of Operation: 2000 cycles.	1.As show in item 3,4 2.Contact Resistance: 100mΩ max. (final-after test)	
	WEATHER-PROOF	13	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1.Temperature : -40°C±3°C 2.Time: 96 hours	As shown in item 2~6
		14	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1.Temperature : 85°C±2°C 2.Time: 96 hours	1.As shown in item 3~6 2.Contact Resistance: 100mΩ max.
15		Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : ①Temperature : 40°C±2°C ②Relative Humidity :90~95% ③Time: 96 hours	1.As shown in item 4,6 2.Contact Resistance: 100mΩ max. 3.Insulation Resistance: 10MΩ min.	

5. SOLDERING CONDITIONS:

■ Condition for Soldering –DM(R) 、 DL(R) –V Series



- The condition mentioned above is the temperature on the Cu foil of the P.C.B surface.

There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc.

Care, therefore, should be used not to allow switch's surface temperature to exceed 260°C.

■ Manual Soldering

Soldering Temperature	Max.350°C
Continuous Soldering Time	Max. 5 seconds

■ Precautions in Handling

1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
2. Don't clean the switch body except with top tape sealed type, which can only spray of cleaning method from top of s/w.
3. Please make sure that there is no flux rose over the surface of the PCB

